

## UNBUMPED FLIP CHIP ARRAY

### APPLICATIONS

- ✓ Cellular Phones
- ✓ MCM Boards
- ✓ Wireless Communication Circuits
- ✓ IR LEDs
- ✓ SMART & PCMCIA Cards

### IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns

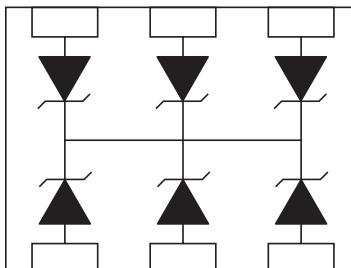
### FEATURES

- ✓ ESD Protection > 25 kilovolts
- ✓ Available in Multiple Voltage Types Ranging From 3.3V to 36V
- ✓ 250 Watts Peak Pulse Power per Line ( $t_p = 8/20\mu s$ )
- ✓ Bidirectional Configuration & Monolithic Structure
- ✓ Protects 3 to 5 Lines
- ✓ RoHS Compliant

### MECHANICAL CHARACTERISTICS

- ✓ Standard EIA Chip Size: 0406
- ✓ Weight 0.73 milligrams (Approximate)
- ✓ Solder Reflow Temperature:
  - Tin-Lead - Sn/Pb: 240-245°C
  - Lead-Free: 260-270°C
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Plastic & Paper Tape and Reel Per EIA Standard 481
- ✓ Device Marking On Reel

### PIN CONFIGURATION



## DEVICE CHARACTERISTICS

### MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

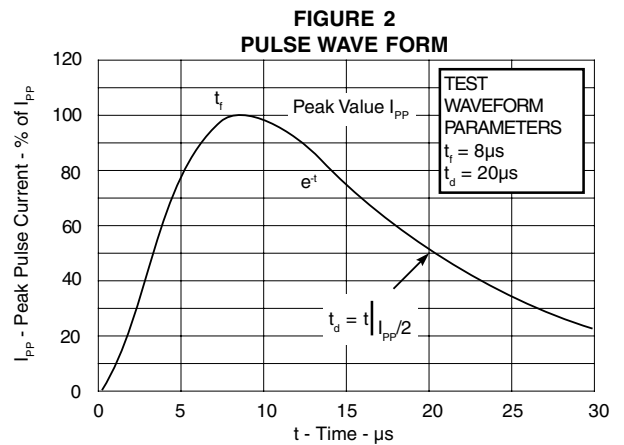
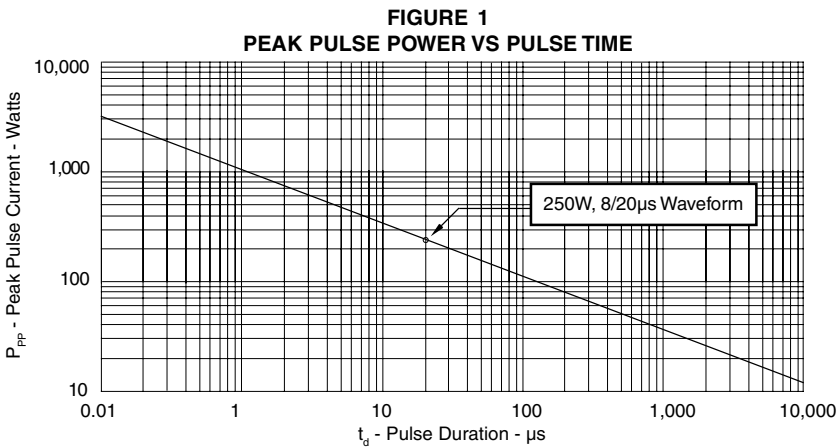
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ( $t_p = 8/20\mu s$ ) - See Figure 1	$P_{PP}$	250	Watts
Operating Temperature	$T_J$	-55°C to 150°C	°C
Storage Temperature	$T_{STG}$	-55°C to 150°C	°C

### ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

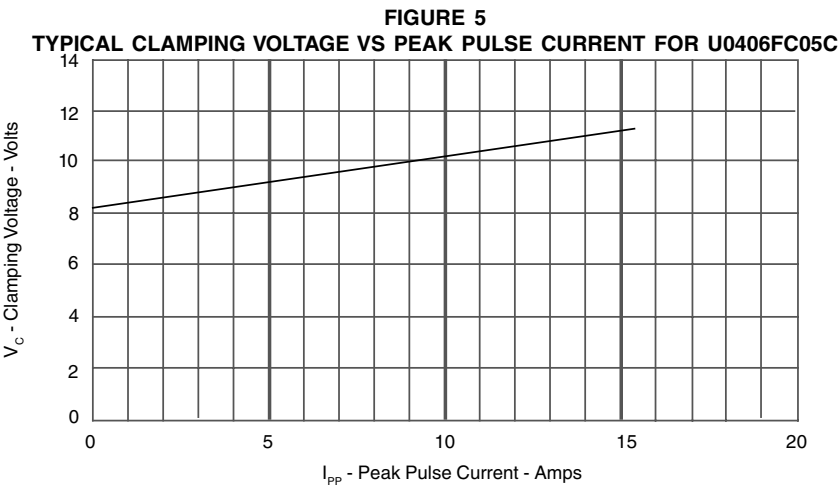
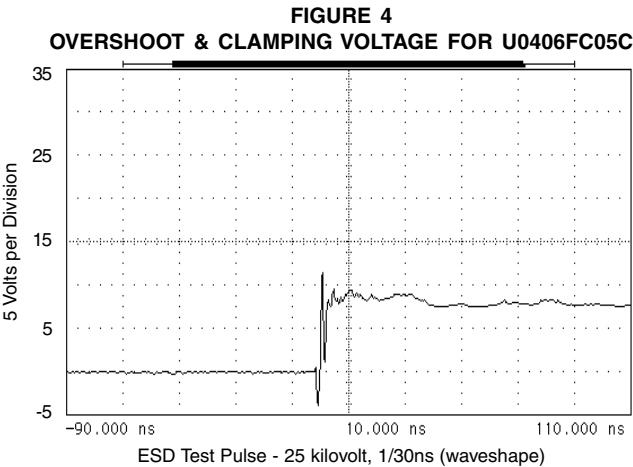
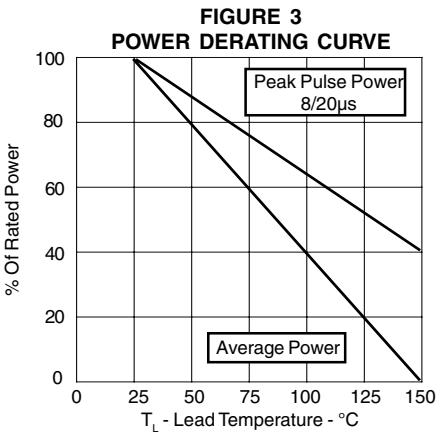
PART NUMBER (See Note 1)	RATED STAND-OFF VOLTAGE $V_{WM}$ VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ $I_P = 1A$ $V_C$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ 8/20 $\mu s$ $V_C$ @ $I_{PP}$	MAXIMUM LEAKAGE CURRENT (See Note 2) @ $V_{WM}$ $I_D$ $\mu A$	TYPICAL CAPACITANCE @ 0V, 1 MHz C pF
U0406FC3.3C	3.3	4.0	7.0	12.5V @ 20A	75*	150
U0406FC05C	5.0	6.0	9.8	14.7V @ 17A	10**	100
U0406FC08C	8.0	8.5	13.4	19.2V @ 13A	10***	75
U0406FC12C	12.0	13.3	19.0	29.7V @ 9.0A	1	50
U0406FC15C	15.0	16.7	24.0	35.7V @ 7.0A	1	40
U0406FC24C	24.0	26.7	43.0	55.0V @ 5.0A	1	30
U0406FC36C	36.0	40.0	64.0	84.0V @ 3.0A	1	25

**Note 1:** All devices are bidirectional. Electrical characteristics apply in both directions.

**Note 2:** \*Maximum leakage current < 5 $\mu A$  @ 2.8V. \*\*Maximum leakage current < 500nA @ 3.3V. \*\*\*Maximum leakage current < 200nA @ 5V.



GRAPHS

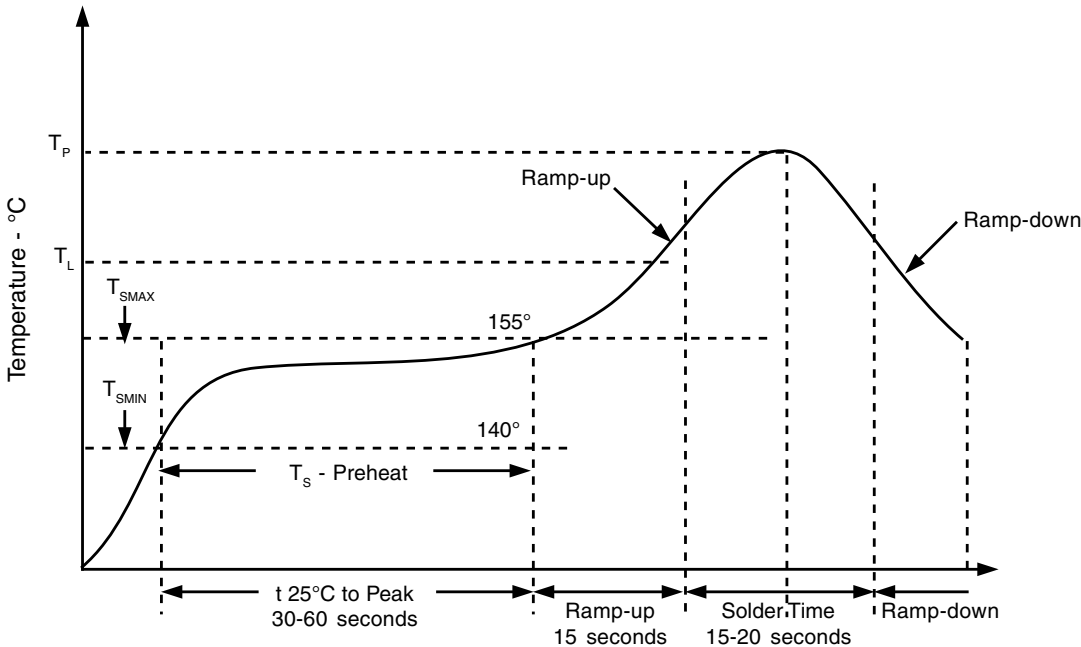
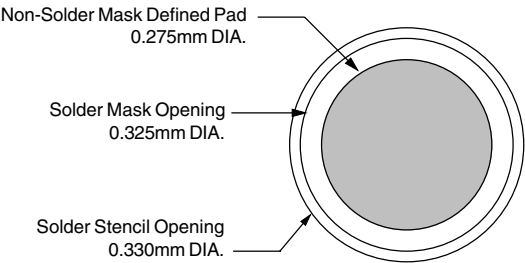


APPLICATION INFORMATION

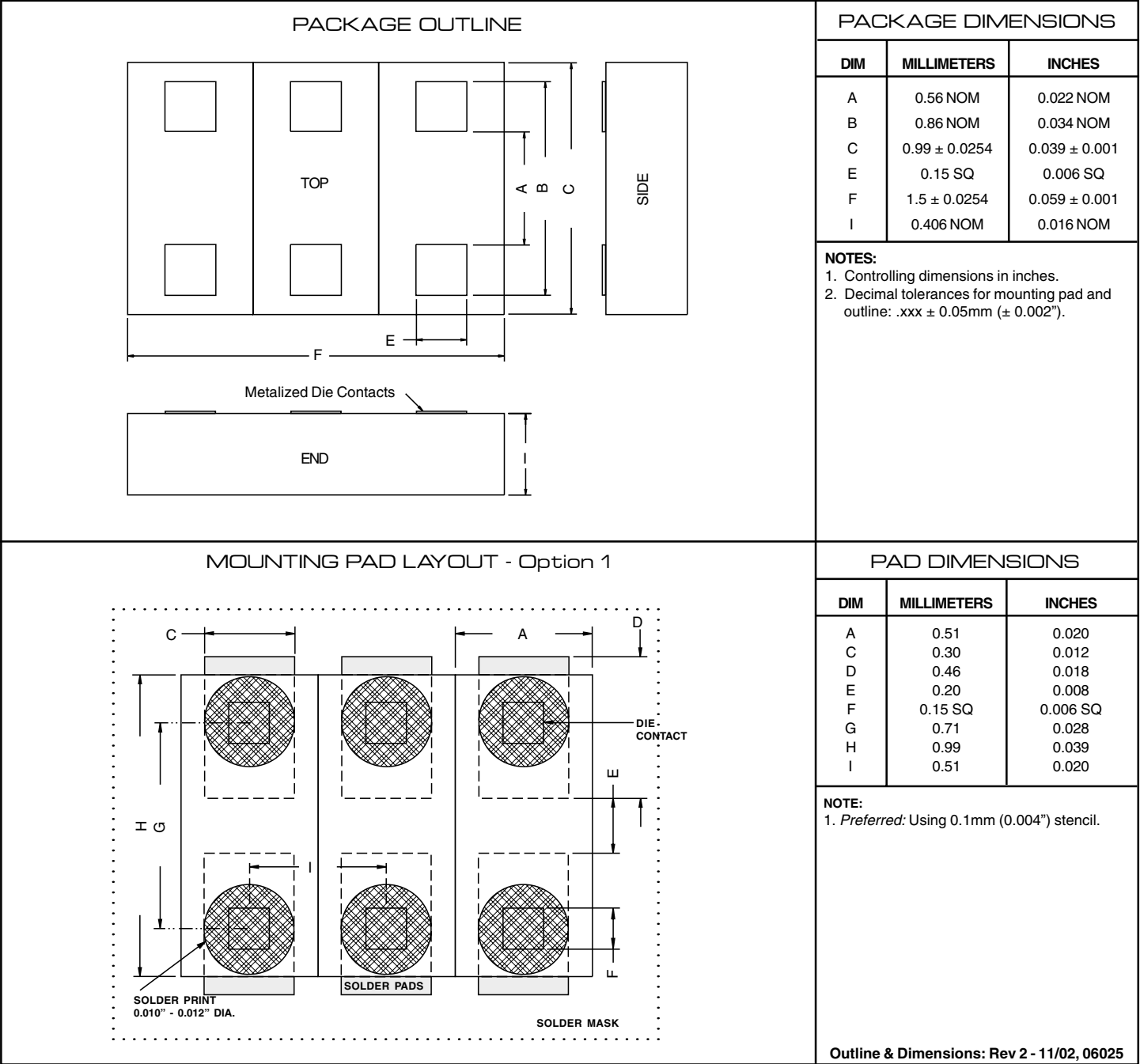
PRINTED CIRCUIT BOARD RECOMMENDATIONS	
PARAMETER	VALUE
Pad Size on PCB	0.275mm
Pad Shape	Round
Pad Definition	Non-Solder Mask Defined Pads
Solder Mask Opening	0.325mm Round
Solder Stencil Thickness	0.150mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.330mm Round
Solder Paste Type	No Clean
Pad Protective Finish	OSP(Entek Cu Plus 106A)
Tolerance - Edge To Corner Ball	±50µm
Solder Ball Side Coplanarity	±20µm
Maximum Dwell Time Above Liquidous (183°C)	60 Seconds
Soldering Maximum Temperature	270°C

REQUIREMENTS
<b>Temperature:</b> T <sub>p</sub> for Lead-Free (SnAgCu): 260-265°C T <sub>p</sub> for Tin-Lead: 240-245°C Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area & plating.

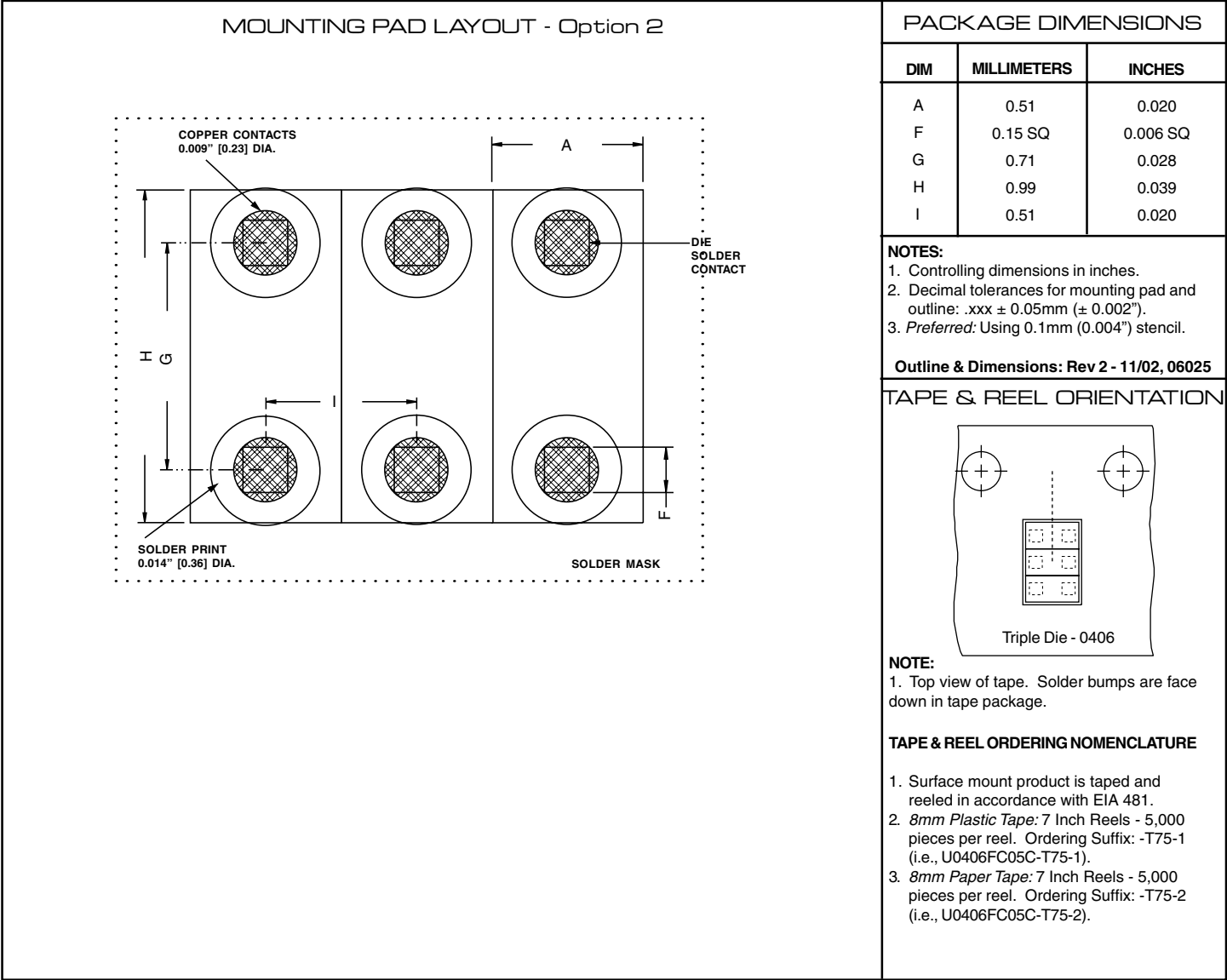
RECOMMENDED NON-SOLDER MASK  
DEFINED PAD ILLUSTRATION



PACKAGE OUTLINE & DIMENSIONS



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**ProTek Devices**  
2929 South Fair Lane, Tempe, AZ 85282  
Tel: 602-431-8101 Fax: 602-431-2288  
E-Mail: [sales@protekdevices.com](mailto:sales@protekdevices.com)  
Web Site: [www.protekdevices.com](http://www.protekdevices.com)